

ABSTRACT

CONDUCTIVE ADHESIVE AND CURED PRODUCT THEREOF

5 There is provided a conductive adhesive which can suppress
erosion of polycarbonate and form a cured product exhibiting excellent
conductivity at a low temperature. There is also provided a
conductive adhesive which can form a cured product exhibiting
excellent adhesive property to plastics (particularly carbonate)
10 at a low temperature.

 The conductive adhesive according to the present invention is
a conductive adhesive which contains the following components (A)
to (C) and is liquid at 25°C:

 component (A): an alicyclic epoxy resin;
15 component (B): a boron-based thermal cationic initiator; and
 component (C): a conductive filler.